

Part Number: DC10GWA

Green

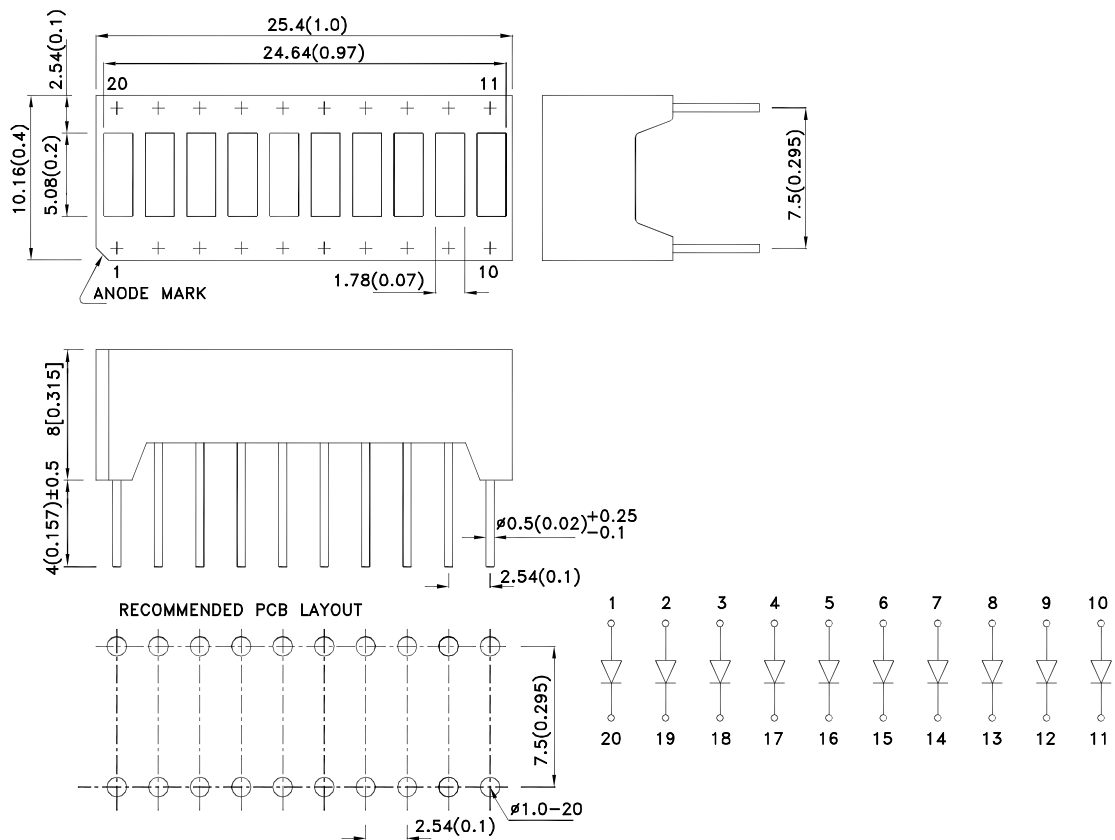
Features

- Suitable for level indicators.
- Low current operation.
- Excellent on/off contrast.
- End stackable.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions & Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
DC10GWA	Green (GaP)	White Diffused	5600	12000	10 Segments Bar graph-Display
			*1400	*4000	

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Green	565		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Green	568		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Green	30		nm	I _F =20mA
C	Capacitance	Green	15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Green	2.2	2.5	V	I _F =20mA
I _R	Reverse Current	Green		10	uA	V _R =5V

Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

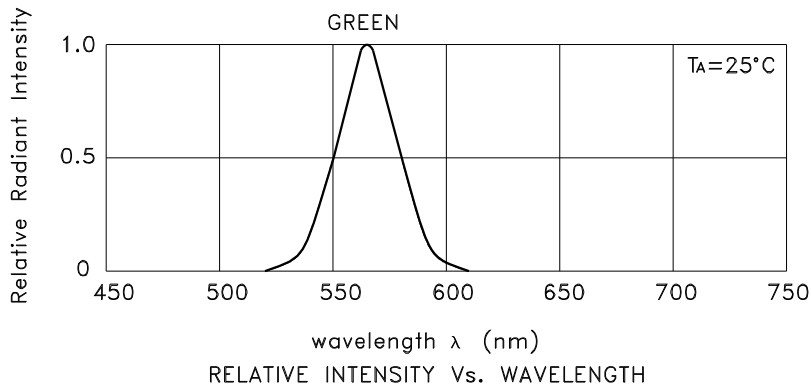
Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units
Power dissipation	62.5	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	
Lead Solder Temperature[2]	260°C For 3-5 Seconds	

Notes:

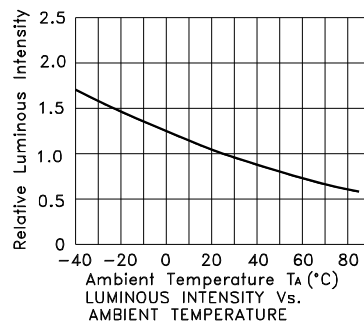
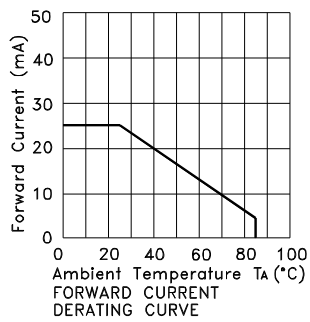
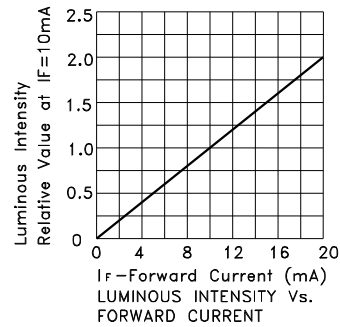
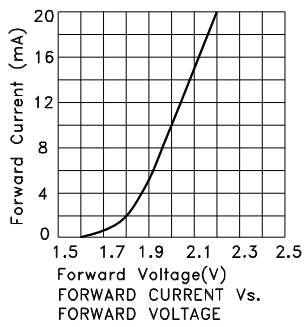
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.



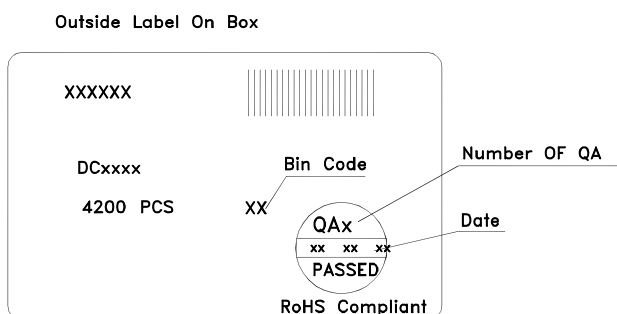
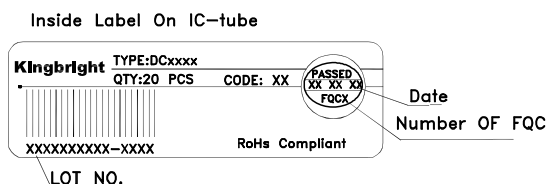
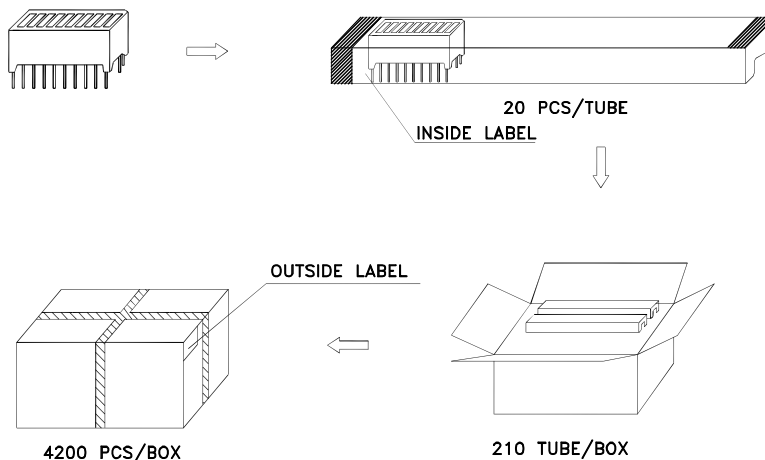
Green

DC10GWA



PACKING & LABEL SPECIFICATIONS

DC10GWA



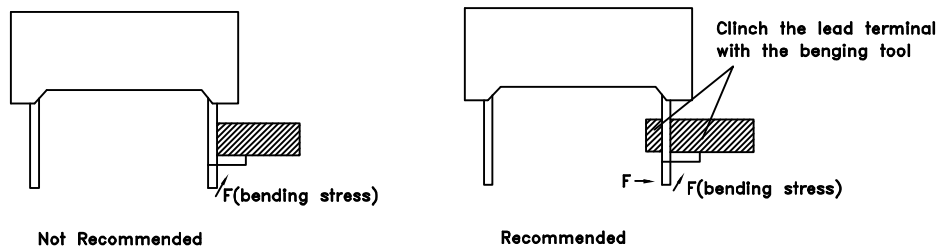
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THROUGH HOLE DISPLAY MOUNTING METHOD

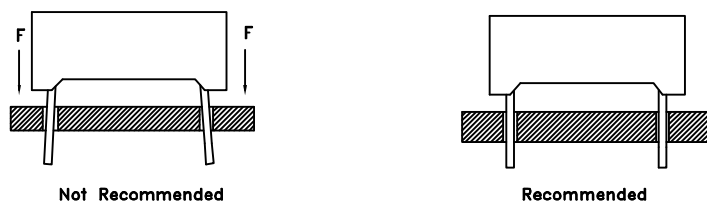
Lead Forming

Do not bend the component leads by hand without proper tools.
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



Installation

1. The installation process should not apply stress to the lead terminals.
2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.

